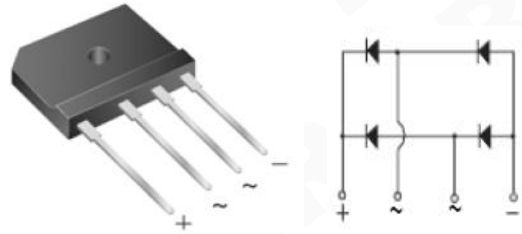




### Features

- Ideal for printed circuit board
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:  
260°C/10 seconds at terminals



### Mechanical Date

- Case: GBJ Molded plastic over glass passivated chip
- **Terminals:**Plated leads solderable per MIL-STD-750,Method 2026
- **Polarity:** Polarity symbols marked on body

### Major Ratings and Characteristics

$I_{F(AV)}$	20 A
$V_{RRM}$	200V to 1000V
$I_{FSM}$	280A
$I_R$	5 $\mu$ A
$V_F$	1.1 V
$T_j$ max.	150 °C

### Maximum Ratings & Thermal Characteristics

( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

Items	Symbol	GBJ 2002	GBJ 2004	GBJ 2006	GBJ 2008	GBJ 2010	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	V
Maximum average forward rectified current at $T_C=90^\circ\text{C}$	$I_{F(AV)}$	20.0					A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	280					A
Thermal resistance from junction to case per leg	$R_{\theta JC}^{(1)}$	1.5					$^\circ\text{C/W}$
$I^2t$ Rating for Fusing ( $t<8.3\text{ms}$ )	$I^2t$	325					$\text{A}^2\text{s}$
RMS isolation voltage from case to leads	$V_{ISO}$	2500					V
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150					$^\circ\text{C}$

Note 1: Junction to case with heatsink

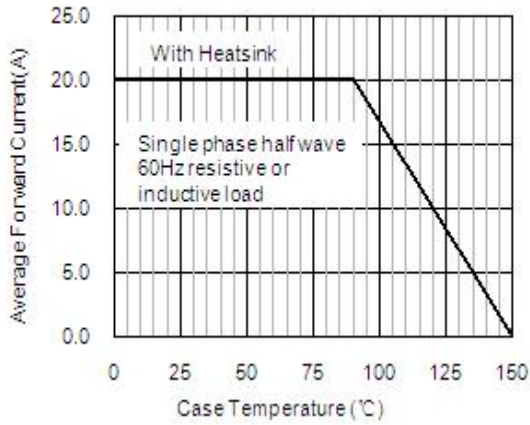
### Electrical Characteristics

( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

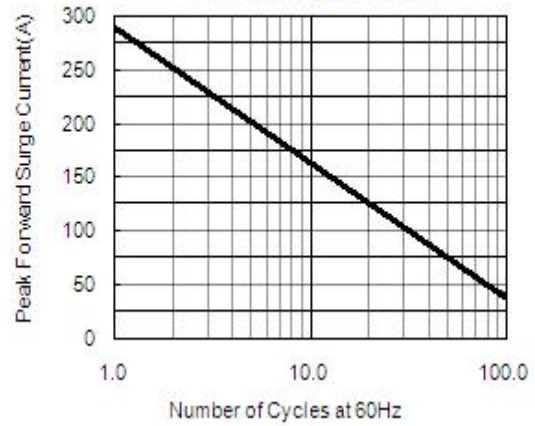
Items	Test conditions	Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage per leg	$I_F=10\text{A}$	$V_F$	-	-	1.10	V
Reverse current per leg	$V_R=V_{DC}$ $T_J=25^\circ\text{C}$ $T_i=125^\circ\text{C}$	$I_R$	-	-	5 500	$\mu\text{A}$

### Characteristic Curves ( $T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

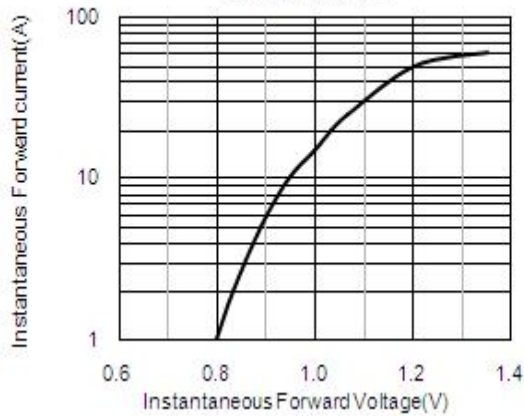
**Fig.1 Forward Current Derating Curve**



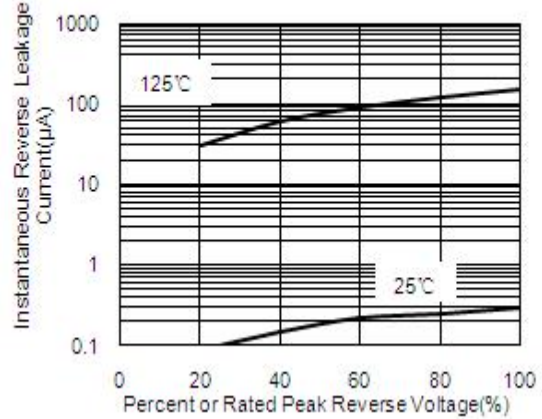
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



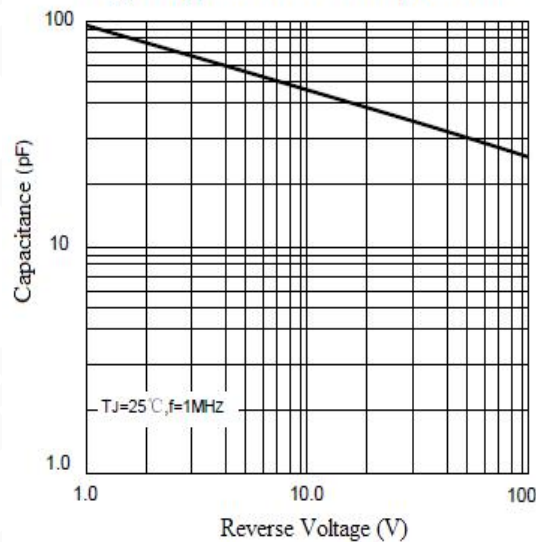
**Fig.3 Typical Instantaneous Forward Characteristics**



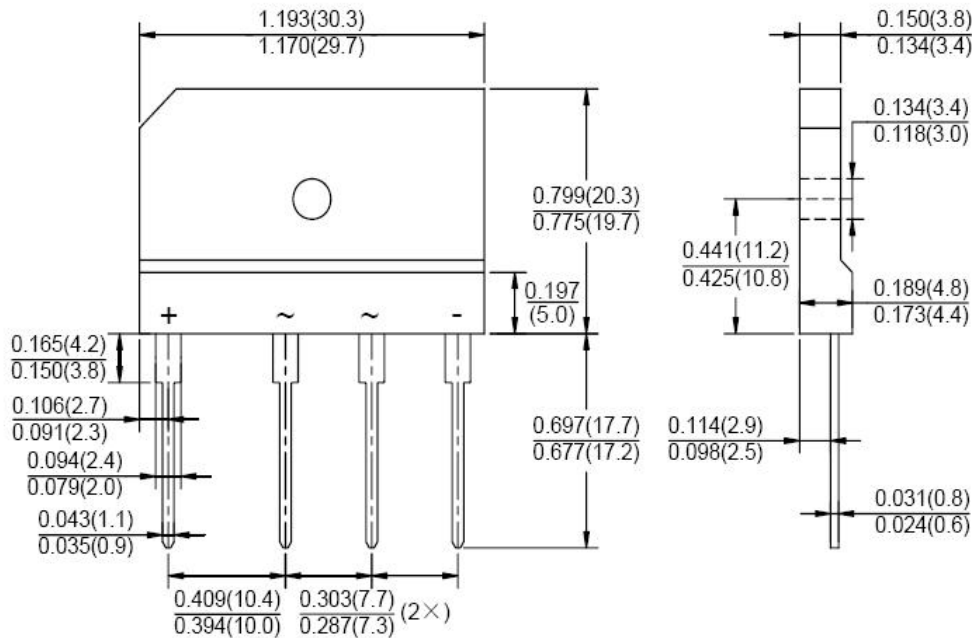
**Fig.4 Typical Reverse Leakage Characteristics**



**Fig.5 Typical Junction Capacitance**



#### Package Outline



Dimensions in inches (mm)

#### Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.

$I_{F(AV)}$ : We recommend that the worst case current be no greater than 80% .

$T_J$ : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a  $T_J$  of below 100°C.

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